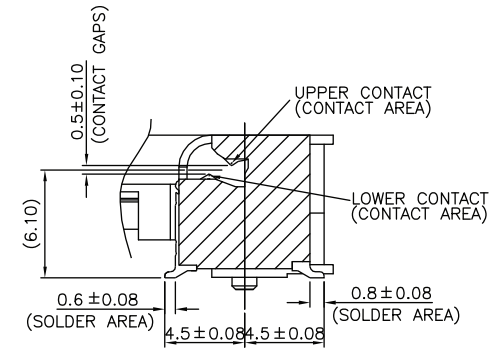
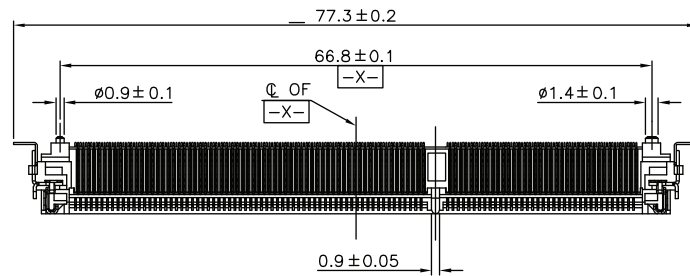
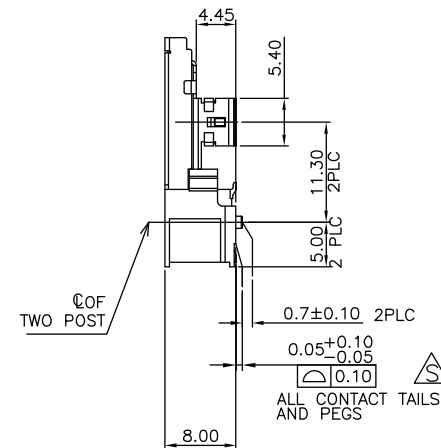
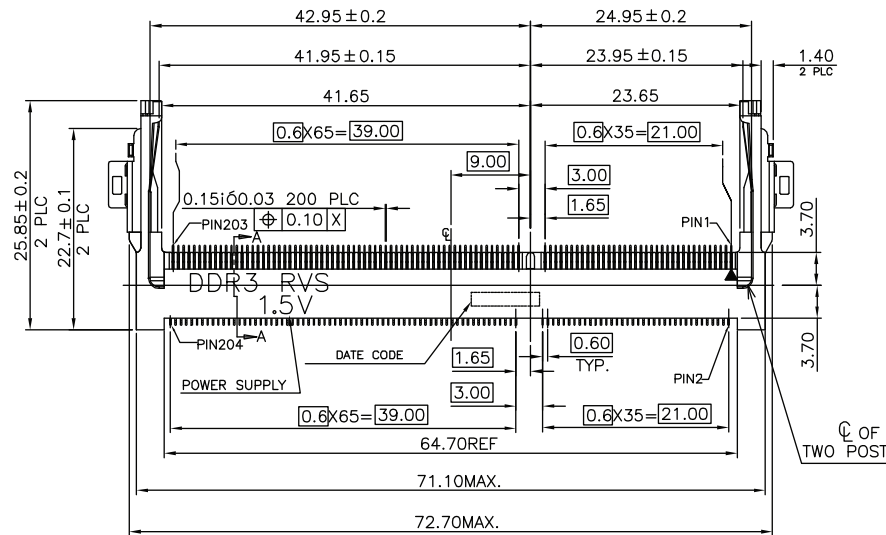


**NOTES:**

1. Recommended Reflow Temperature 260°C ( 5 Sec.)
2. Voltage Rating: 25 VAC
3. Current Rating: 0.5 A
4. Temperature Rating: -55 C to 85 C



CROSS SECTIONAL A-A



**HOW TO ORDER:**

**B 0 3 0 - 2 0 4 3 - D 1 X X - Z**

**NUMBER OF CONTACTS:**  
204

**HEIGHT OPTION:**  
D - 8.0mm

**ORIENTATION:**  
1 - Reverse

**PLATING OPTIONS:**  
2 - Au FLASH  
6 - 15u" Au

**RoHS COMPLIANT**

**PACKAGING:**  
0 - Tray  
1 - Tape & Reel (Normal)  
2 - Tape & Reel (Reverse)

**KEY TYPE / VOLTAGE OPTION :**  
3 - 1.5V TYPE

**MATERIAL:**

CONTACT PLATING: Specified Au Thickness in Contact Area  
Au Flash on Solder Tails; 50u" Nickel Sub Plate  
Nickel Sub Plate (80"m min)  
HOUSING: High Temp Thermo Plastic UL94V-0, Black  
METAL LATCH: Stainless Steel  
FLOATING LATCH: Stainless Steel  
FIXED LATCH: Stainless Steel  
CONTACT: Copper Alloy

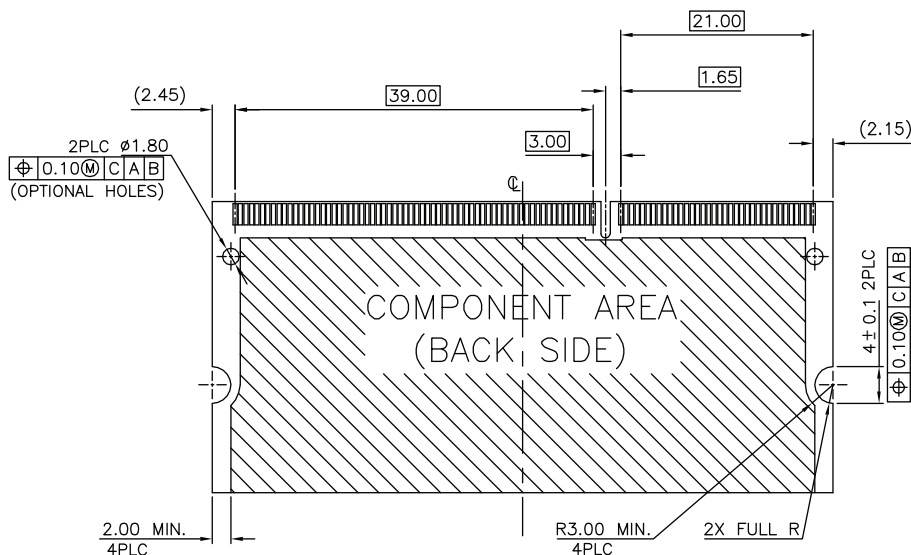
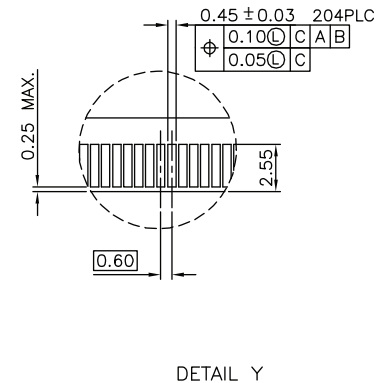
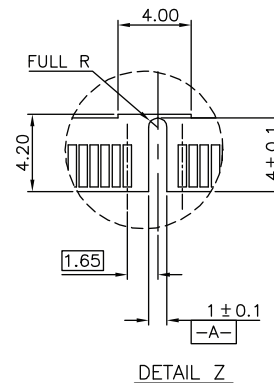
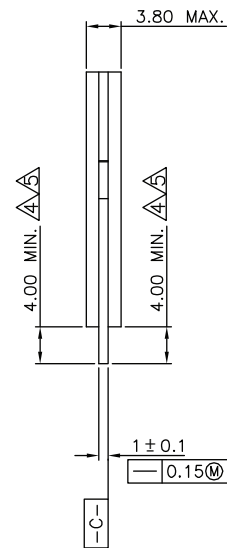
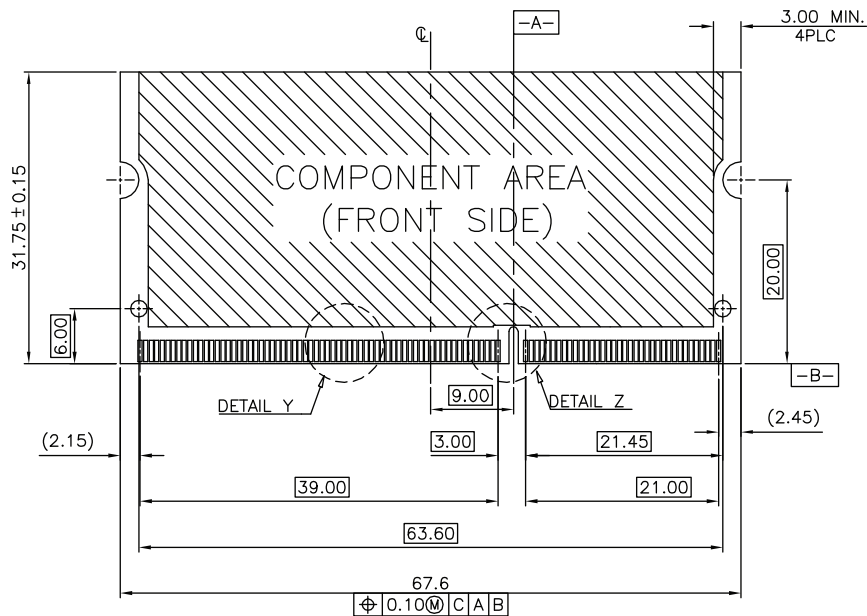
Rev	Description	Drawn	Checked	Approved	Date
0	Issued	B.S.	S.M.	S.M.	09/02/10
TOL. DEC.	.X +/- 0.40	.XX +/- 0.25	.XXX +/- 0.15	.XXXX +/- 0.05	ANGLE +/- 3° UNIT: mm

**SMP TECHNOLOGY, INC.**

DDR SO DIMM Socket, 204 Position, 1.5 Volt

Reverse Orientation, Right Angle, 8.0mm Height, Type 2

P/N: B030-2043-D1XX-Z



NOTE:

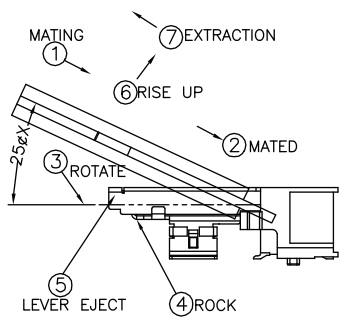
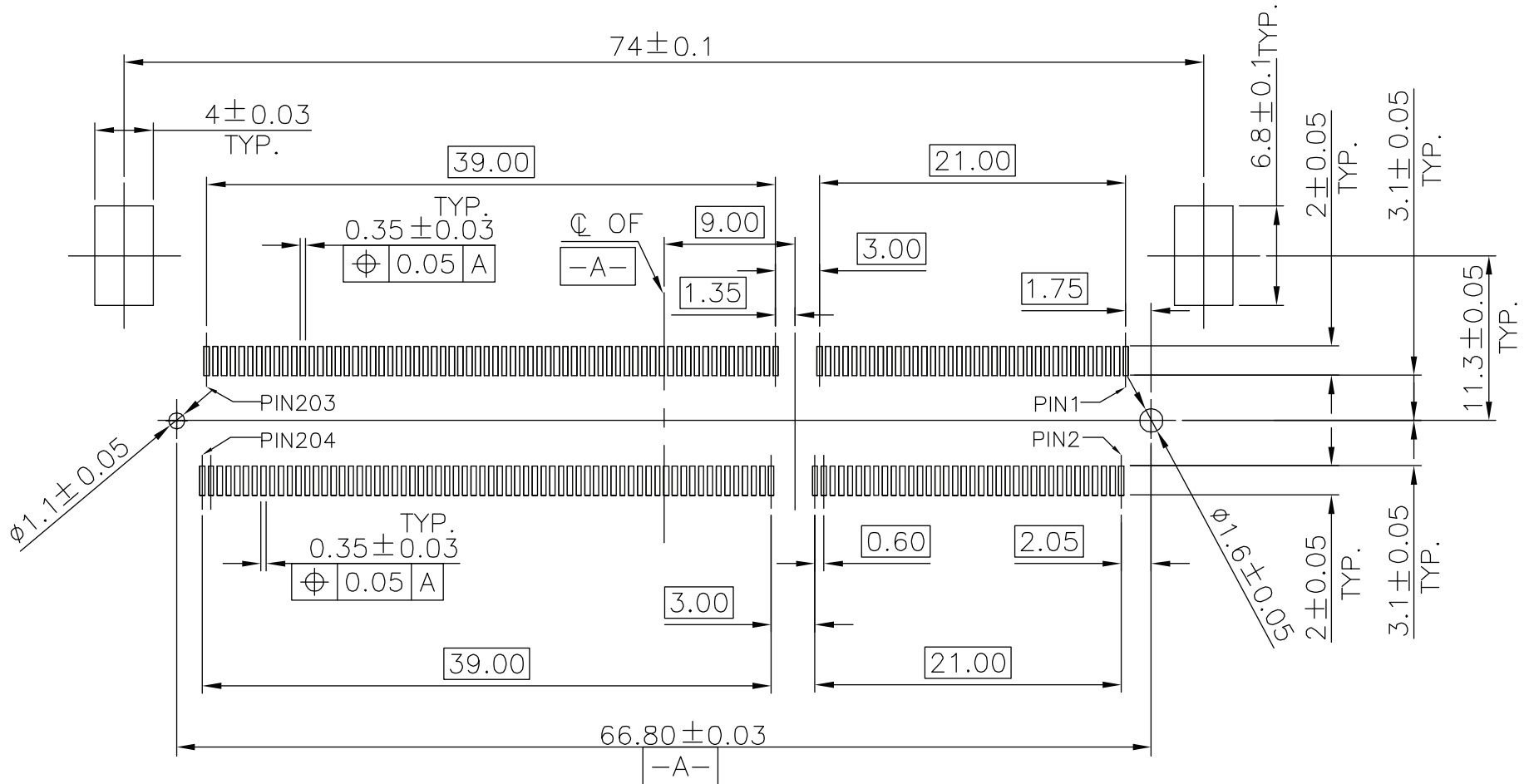
1. TOLERANCES ON ALL DIMENSIONS ±0.15 UNLESS OTHERWISE SPECIFIED.
  2. P.C.BOARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR MENTAIZATION.
  3. FINISH OF PAD:GOLD PLATING 0.00076MIN OVER ON PLATING 0.002MIN.
- ▲ DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON BOTH SIDE.  
PCB THICKNESS NOT TO BE EXCEEDED OUTSIDE OF COMPONENT AREA.  
▲ BORDER OF COMPONENT AREA.

RECOMMENDED MATING P.C.B CONFIGURATION

**SMP TECHNOLOGY, INC.**

DDR SO DIMM Socket, 204 Position, 1.5 Volt

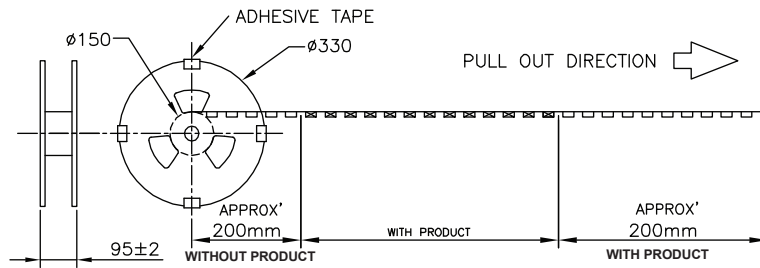
Reverse Orientation, Right Angle, 8.0mm Height, Type 2



HOW TO MATE AND UNMATE  
 MATE: ① → ④  
 UNMATE: ⑤ → ⑦

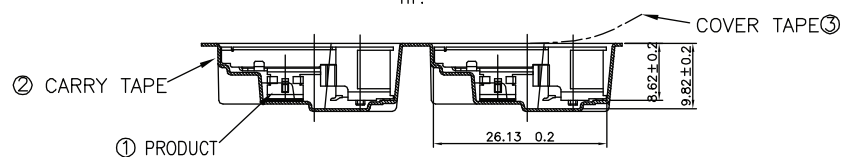
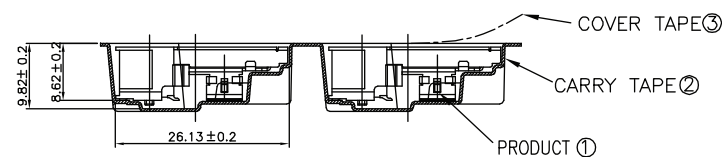
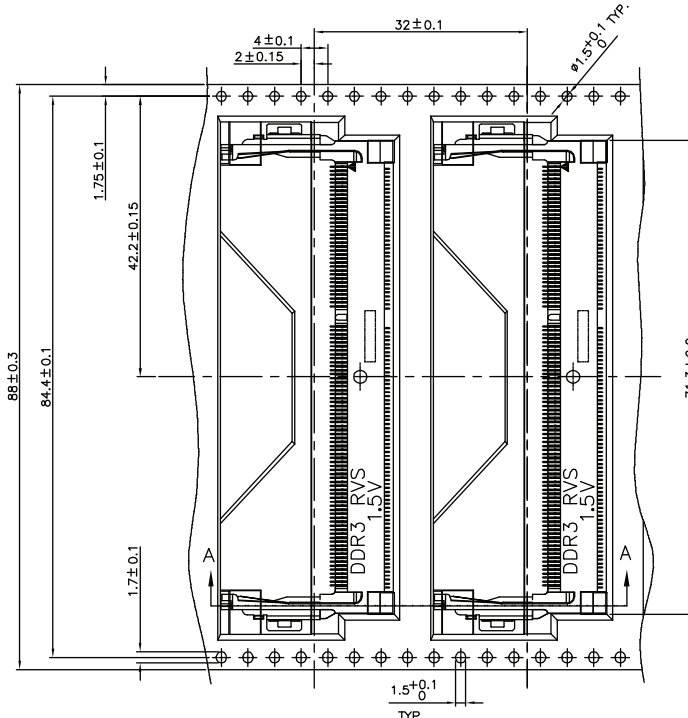
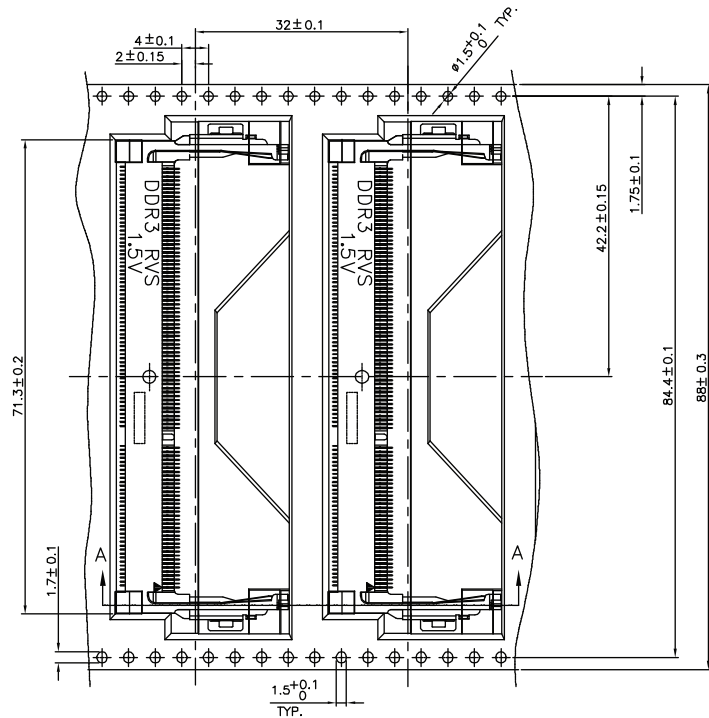
RECOMMENDED PCB LAYOUT  
 THICKNESS: 1.6±0.05mm

<b>SMP TECHNOLOGY, INC.</b>	
DDR SO DIMM Socket, 204 Position, 1.5 Volt	
Reverse Orientation, Right Angle, 8.0mm Height, Type 2	



NOTES:

1. PACKAGING MATERIAL IN PLASTIC, RUBBER, INK, PIGMENT AND MUST MEET CONTROLLED SUBSTANCES SPEC PER WI-PB-22.  
\* CADMIUM AND CADMIUM COMPOUNDS NOT TO EXCEED : 5 PPM.  
\* LEAD, CADMIUM, CHROMIUM VI AND MERCURY NOT TO EXCEED : 100 PPM (COMBINED)
2. CARRIER TAPES, COVER TAPES, REELS AND TAPED COMPONENTS MUST MEET THE REQUIREMENTS DEFINED PER EIA-481-B.
3. DIMENSION :  
3.1 REEL : H = 95,  $\phi A = 330$   
3.2 SHIPPING CARTON : L = 335, W = 335, H = 248
4. QUANTITY :  
4.1 PRIMARY PACKAGING : 150PCS / REEL  
4.2 SECONDARY PACKAGING : 2 REELS / CARTON (300PCS)
5. WEIGHT :  
5.1 NET WEIGHT : 1.58Kg / REEL, 3.16 Kg / CARTON.  
5.2 GROSS WEIGHT : 2.03 Kg / REEL, 4.05 Kg / CARTON
6. PEELING RESISTANCE : 0.1~0.7N (10.2gf ~ 71.4gf)
7. PEELING SPEED : 300mm / MINUTE.



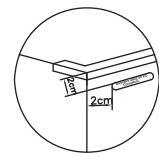
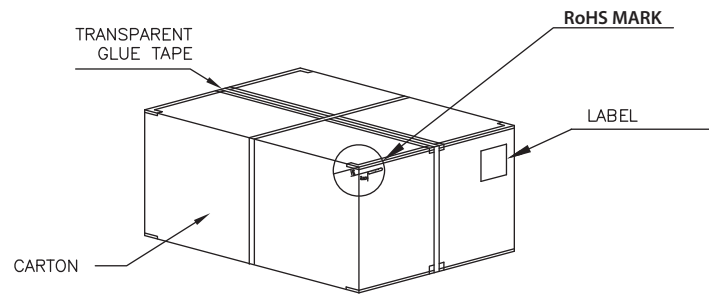
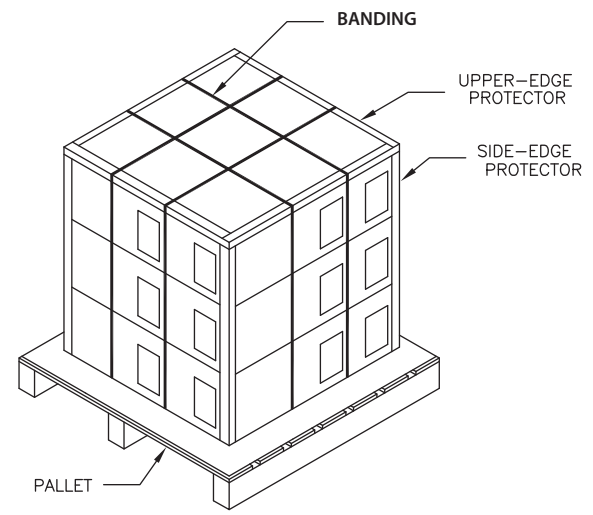
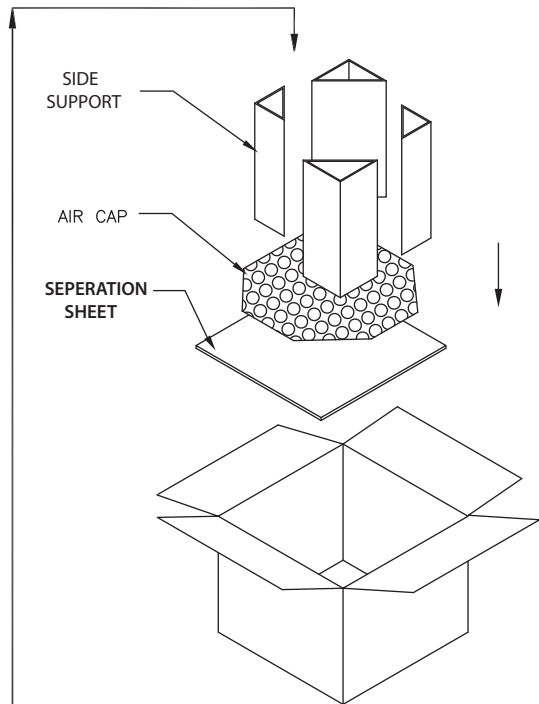
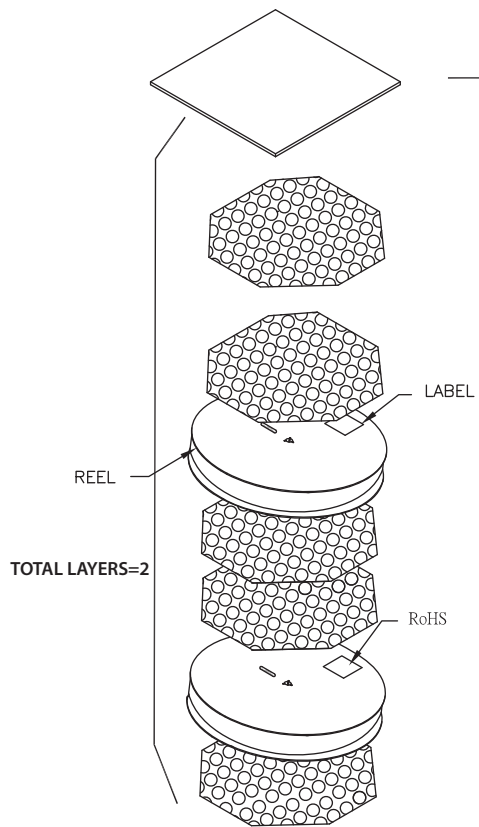
Section A-A  
Packaging Direction: Tape & Reel Normal

Section A-A  
Packaging Direction: Tape & Reel Reverse

**SMP TECHNOLOGY, INC.**

DDR SO DIMM Socket, 204 Position, 1.5 Volt

Reverse Orientation, Right Angle, 8.0mm Height, Type 2



<b>SMP TECHNOLOGY, INC.</b>	
DDR SO DIMM Socket, 204 Position, 1.5 Volt	
Reverse Orientation, Right Angle, 8.0mm Height, Type 2	
P/N: B 0 3 0 - 2 0 4 3 - D 1 X X - Z	Pg: 5 of 5